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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	3 ns
Voltage Supply - Internal	1.65V ~ 1.95V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256c-3t176c

Table 2. ispMACH 4000Z Family Selection Guide

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t _{PD} (ns)	3.5	3.7	4.2	4.5
t _S (ns)	2.2	2.5	2.7	2.9
t _{CO} (ns)	3.0	3.2	3.5	3.8
f _{MAX} (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I _{cc} (μ A)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

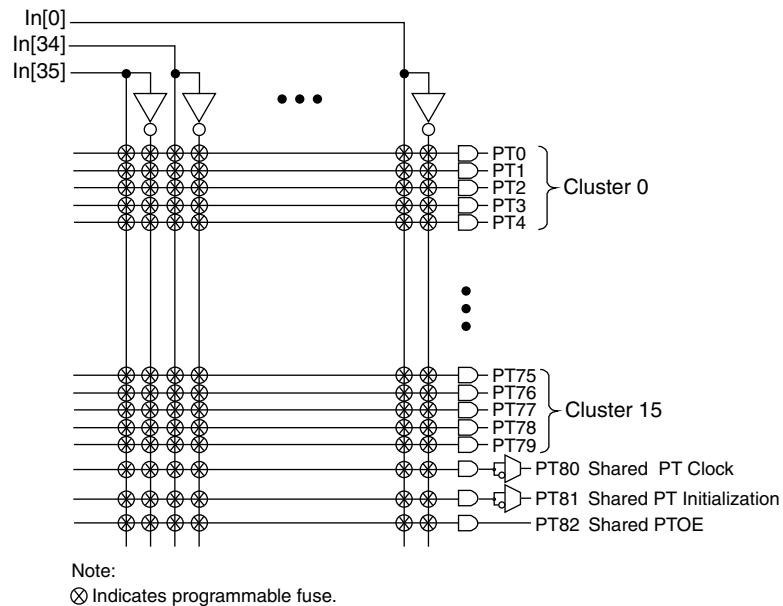
The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V_{CC} (logic core).

Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Figure 3. AND Array

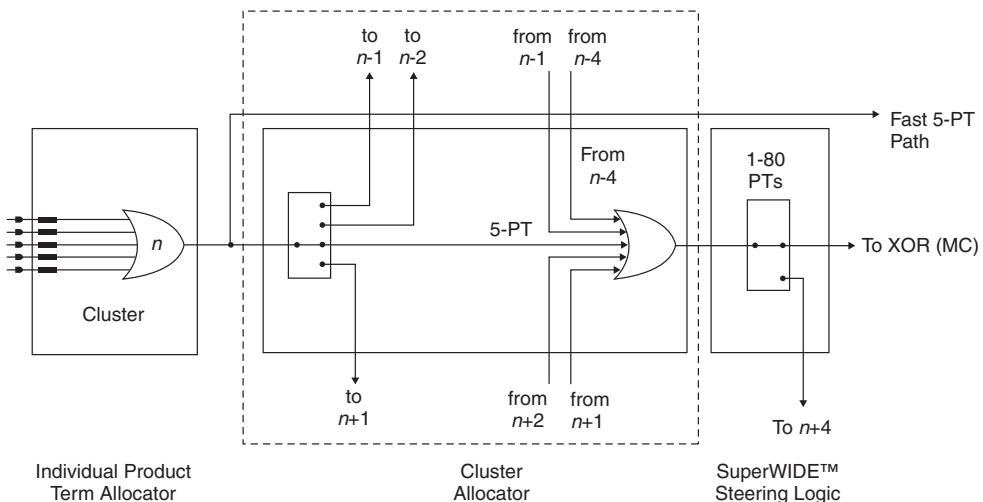
Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

Figure 4. Macrocell Slice

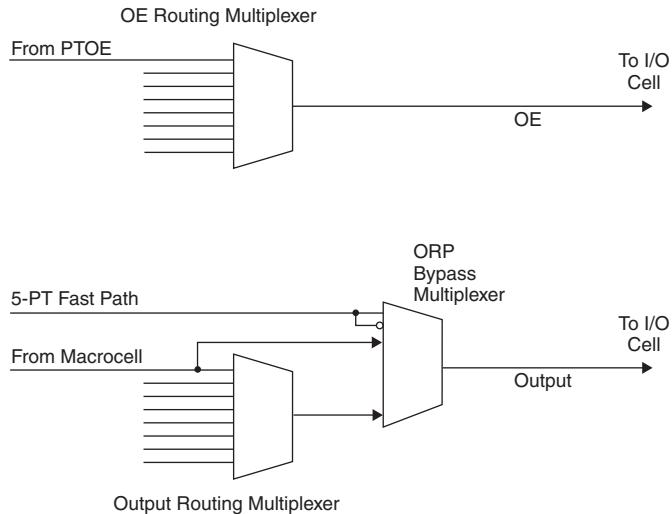
Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

Figure 7. ORP Slice



Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

Table 6. ORP Combinations for I/O Blocks with 8 I/Os

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

- LVTTL
- LVC MOS 1.8
- LVC MOS 3.3
- 3.3V PCI Compatible
- LVC MOS 2.5

All of the I/Os and dedicated inputs have the capability to provide a bus-keeper latch, Pull-up Resistor or Pull-down Resistor. A fourth option is to provide none of these. The selection is done on a global basis. The default in both hardware and software is such that when the device is erased or if the user does not specify, the input structure is configured to be a Pull-up Resistor.

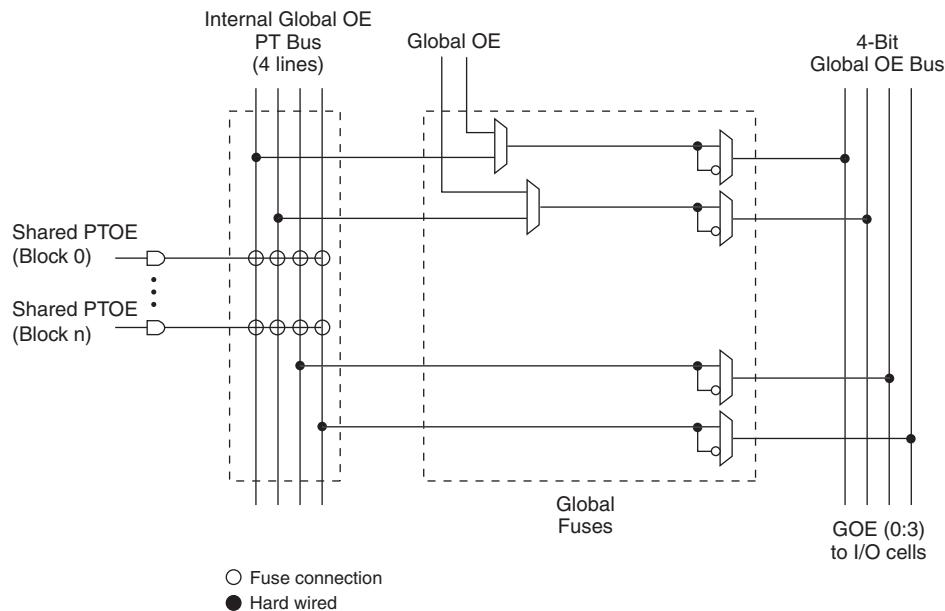
Each ispMACH 4000 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for fast slew or slow slew. The typical edge rate difference between fast and slow slew setting is 20%. For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed.

Global OE Generation

Most ispMACH 4000 family devices have a 4-bit wide Global OE Bus, except the ispMACH 4032 device that has a 2-bit wide Global OE Bus. This bus is derived from a 4-bit internal global OE PT bus and two dual purpose I/O or GOE pins. Each signal that drives the bus can optionally be inverted.

Each GLB has a block-level OE PT that connects to all bits of the Global OE PT bus with four fuses. Hence, for a 256-macrocell device (with 16 blocks), each line of the bus is driven from 16 OE product terms. Figures 9 and 10 show a graphical representation of the global OE generation.

Figure 9. Global OE Generation for All Devices Except ispMACH 4032



Absolute Maximum Ratings^{1,2,3}

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied ^{4,5}	-0.5 to 5.5V	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C	-65 to 150°C
Junction Temperature (T_j) with Power Applied	-55 to 150°C	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of (V_{IH} (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with $V_{IN} > 3.6V$ is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
V_{CC}	ispMACH 4000C	1.65	1.95	V
	ispMACH 4000Z	1.7	1.9	V
	ispMACH 4000Z, Extended Functional Voltage Operation	1.6 ^{1,2}	1.9	V
	Supply Voltage for 2.5V Devices	2.3	2.7	V
T_j	Supply Voltage for 3.3V Devices	3.0	3.6	V
	Junction Temperature (Commercial)	0	90	C
	Junction Temperature (Industrial)	-40	105	C
	Junction Temperature (Extended)	-40	130	C

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

Hot Socketing Characteristics^{1,2,3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq 3.0V, T_j = 105^\circ C$	—	± 30	± 150	μA
		$0 \leq V_{IN} \leq 3.0V, T_j = 130^\circ C$	—	± 30	± 200	μA

1. In insensitive to sequence of V_{CC} or V_{CCO} . However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO} , provided $(V_{IN} - V_{CCO}) \leq 3.6V$.
2. $0 < V_{CC} < V_{CC}$ (MAX), $0 < V_{CCO} < V_{CCO}$ (MAX).
3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} . Device defaults to pull-up until fuse circuitry is active.

ispMACH 4000V/B/C Internal Timing Parameters (Cont.)

Over Recommended Operating Conditions

Parameter	Description	-2.5		-2.7		-3		-3.5		Units
t_{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	—	0.25	ns
t_{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	0.28	—	0.28	—	0.28	—	0.28	—	ns
t_{SRR}	Asynchronous Reset or Set Recovery Time	1.67	—	1.67	—	1.67	—	1.67	—	ns
Control Delays										
t_{BCLK}	GLB PT Clock Delay	—	1.12	—	1.12	—	1.12	—	1.12	ns
t_{PTCLK}	Macrocell PT Clock Delay	—	0.87	—	0.87	—	0.87	—	0.87	ns
t_{BSR}	Block PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	—	1.83	ns
t_{PTSR}	Macrocell PT Set/Reset Delay	—	1.11	—	1.41	—	1.51	—	1.61	ns
t_{GPOE}	Global PT OE Delay	—	2.83	—	4.13	—	5.33	—	5.33	ns
t_{PTOE}	Macrocell PT OE Delay	—	1.83	—	2.13	—	2.33	—	2.83	ns

Timing v.3.2

Note: Internal Timing Parameters are not tested and are for reference only. Refer to the Timing Model in this data sheet for further details.

ispMACH 4000Z Timing Adders¹

Adder Type	Base Parameter	Description	-35		-37		-42		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
Optional Delay Adders									
t _{INDIO}	t _{INREG}	Input register delay	—	1.00	—	1.00	—	1.30	ns
t _{EXP}	t _{MCELL}	Product term expander delay	—	0.40	—	0.40	—	0.45	ns
t _{ORP}	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t _{BLA}	t _{ROUTE}	Additional block loading adder	—	0.04	—	0.05	—	0.05	ns
t_{IOI} Input Adjusters									
LVTTL_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t _{IN} , t _{GCLK_IN} , t _{GOE}	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
t_{IOO} Output Adjusters									
LVTTL_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t _{BUF} , t _{EN} , t _{DIS}	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t _{BUF} , t _{EN}	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding the use of these adders.

ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:
44-Pin TQFP

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

ispMACH 4032Z and 4064Z Logic Signal Connections: 56-Ball csBGA (Cont.)

Ball Number	Bank Number	ispMACH 4032Z		ispMACH 4064Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
K5	0	A15	A^15	B0	B^0
H6	0	CLK1/I	-	CLK1/I	-
K6	1	CLK2/I	-	CLK2/I	-
H7	1	B0	B^0	C0	C^0
K7	1	B1	B^1	C1	C^1
K8	1	B2	B^2	C2	C^2
K9	1	B3	B^3	C4	C^3
K10	1	B4	B^4	C6	C^4
J10	-	TMS	-	TMS	-
H8	1	B5	B^5	C8	C^5
H10	1	B6	B^6	C10	C^6
G10	1	B7	B^7	C11	C^7
G8	1	GND (Bank 1)	-	GND (Bank 1)	-
F8	1	NC ¹	-	I ¹	-
F10	1	NC ¹	-	I ¹	-
E8	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
E10	1	B8	B^8	D15	D^7
D8	1	B9	B^9	D12	D^6
D10	1	B10	B^10	D10	D^5
C10	1	B11	B^11	D8	D^4
B10	1	NC ¹	-	I ¹	-
A10	-	TDO	-	TDO	-
A9	-	VCC	-	VCC	-
C8	-	GND	-	GND	-
A8	1	NC ¹	-	I ¹	-
A7	1	B12	B^12	D6	D^3
C7	1	B13	B^13	D4	D^2
C6	1	B14	B^14	D2	D^1
A6	1	B15/GOE1	B^15	D0/GOE1	D^0
C5	1	CLK3/I	-	CLK3/I	-
A5	0	CLK0/I	-	CLK0/I	-
C4	0	A0/GOE0	A^0	A0/GOE0	A^0
A4	0	A1	A^1	A1	A^1
A3	0	A2	A^2	A2	A^2
A2	0	A3	A^3	A4	A^3
A1	0	A4	A^4	A6	A^4

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4064Z devices.

**ispMACH 4064V/B/C/Z, 4128V/B/C/Z, 4256V/B/C/Z Logic Signal Connections:
100-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4064V/B/C/Z		ispMACH 4128V/B/C/Z		ispMACH 4256V/B/C/Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
42	1	C1	C^1	E2	E^1	I6	I^1
43	1	C2	C^2	E4	E^2	I10	I^2
44	1	C3	C^3	E6	E^3	I12	I^3
45	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
46	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
47	1	C4	C^4	E8	E^4	J2	J^0
48	1	C5	C^5	E10	E^5	J6	J^1
49	1	C6	C^6	E12	E^6	J10	J^2
50	1	C7	C^7	E14	E^7	J12	J^3
51	-	GND	-	GND	-	GND	-
52	-	TMS	-	TMS	-	TMS	-
53	1	C8	C^8	F0	F^0	K12	K^3
54	1	C9	C^9	F2	F^1	K10	K^2
55	1	C10	C^10	F4	F^2	K6	K^1
56	1	C11	C^11	F6	F^3	K2	K^0
57	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
58	1	C12	C^12	F8	F^4	L12	L^3
59	1	C13	C^13	F10	F^5	L10	L^2
60	1	C14	C^14	F12	F^6	L6	L^1
61	1	C15	C^15	F13	F^7	L4	L^0
62*	1	I	-	I	-	I	-
63	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
64	1	D15	D^15	G14	G^7	M4	M^0
65	1	D14	D^14	G12	G^6	M6	M^1
66	1	D13	D^13	G10	G^5	M10	M^2
67	1	D12	D^12	G8	G^4	M12	M^3
68	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
69	1	D11	D^11	G6	G^3	N2	N^0
70	1	D10	D^10	G5	G^2	N6	N^1
71	1	D9	D^9	G4	G^1	N10	N^2
72	1	D8	D^8	G2	G^0	N12	N^3
73*	1	I	-	I	-	I	-
74	-	TDO	-	TDO	-	TDO	-
75	-	VCC	-	VCC	-	VCC	-
76	-	GND	-	GND	-	GND	-
77*	1	I	-	I	-	I	-
78	1	D7	D^7	H13	H^7	O12	O^3
79	1	D6	D^6	H12	H^6	O10	O^2
80	1	D5	D^5	H10	H^5	O6	O^1
81	1	D4	D^4	H8	H^4	O2	O^0
82	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
D13	1	D10	D^10	G4	G^3	N6	N^3
D14	1	D9	D^9	G2	G^2	N8	N^4
D12	1	D8	D^8	G1	G^1	N10	N^5
C14	1	I	-	G0	G^0	N12	N^6
C13	1	NC	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B14	-	TDO	-	TDO	-	TDO	-
A14	-	VCC	-	VCC	-	VCC	-
A13	-	GND	-	GND	-	GND	-
B13	1	NC	-	H14	H^11	O12	O^6
A12	1	I	-	H13	H^10	O10	O^5
C12	1	D7	D^7	H12	H^9	O8	O^4
B12	1	D6	D^6	H10	H^8	O6	O^3
A11	1	D5	D^5	H9	H^7	O4	O^2
C11	1	D4	D^4	H8	H^6	O2	O^1
B11	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
A10	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B10	1	NC	-	H6	H^5	P12	P^6
C10	1	NC	-	H5	H^4	P10	P^5
B9	1	D3	D^3	H4	H^3	P8	P^4
A9	1	D2	D^2	H2	H^2	P6	P^3
C9	1	D1	D^1	H1	H^1	P4	P^2
A8	1	D0/GOE1	D^0	H0/GOE1	H^0	P2/GOE1	P^1
B8	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
C8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
B7	-	VCC	-	VCC	-	VCC	-
A7	0	NC ¹	-	NC ¹	-	I ¹	-
C7	0	A0/GOE0	A^0	A0/GOE0	A^0	A2/GOE0	A^1
A6	0	A1	A^1	A1	A^1	A4	A^2
B6	0	A2	A^2	A2	A^2	A6	A^3
C6	0	A3	A^3	A4	A^3	A8	A^4
B5	0	NC	-	A5	A^4	A10	A^5
A5	0	NC	-	A6	A^5	A12	A^6
C5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
A4	0	NC	-	A8	A^6	B2	B^1
C4	0	A4	A^4	A9	A^7	B4	B^2
A3	0	A5	A^5	A10	A^8	B6	B^3
B3	0	A6	A^6	A12	A^9	B8	B^4
A2	0	A7	A^7	A13	A^10	B10	B^5
A1	0	NC	-	A14	A^11	B12	B^6

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4256Z device.

ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4128V	LC4128V-27T144C	128	3.3	2.7	TQFP	144	96	C
	LC4128V-5T144C	128	3.3	5	TQFP	144	96	C
	LC4128V-75T144C	128	3.3	7.5	TQFP	144	96	C
	LC4128V-27T128C	128	3.3	2.7	TQFP	128	92	C
	LC4128V-5T128C	128	3.3	5	TQFP	128	92	C
	LC4128V-75T128C	128	3.3	7.5	TQFP	128	92	C
	LC4128V-27T100C	128	3.3	2.7	TQFP	100	64	C
	LC4128V-5T100C	128	3.3	5	TQFP	100	64	C
	LC4128V-75T100C	128	3.3	7.5	TQFP	100	64	C
LC4256V	LC4256V-3FT256AC	256	3.3	3	ftBGA	256	128	C
	LC4256V-5FT256AC	256	3.3	5	ftBGA	256	128	C
	LC4256V-75FT256AC	256	3.3	7.5	ftBGA	256	128	C
	LC4256V-3FT256BC	256	3.3	3	ftBGA	256	160	C
	LC4256V-5FT256BC	256	3.3	5	ftBGA	256	160	C
	LC4256V-75FT256BC	256	3.3	7.5	ftBGA	256	160	C
	LC4256V-3F256AC ¹	256	3.3	3	fpBGA	256	128	C
	LC4256V-5F256AC ¹	256	3.3	5	fpBGA	256	128	C
	LC4256V-75F256AC ¹	256	3.3	7.5	fpBGA	256	128	C
	LC4256V-3F256BC ¹	256	3.3	3	fpBGA	256	160	C
	LC4256V-5F256BC ¹	256	3.3	5	fpBGA	256	160	C
	LC4256V-75F256BC ¹	256	3.3	7.5	fpBGA	256	160	C
	LC4256V-3T176C	256	3.3	3	TQFP	176	128	C
	LC4256V-5T176C	256	3.3	5	TQFP	176	128	C
	LC4256V-75T176C	256	3.3	7.5	TQFP	176	128	C
	LC4256V-3T144C	256	3.3	3	TQFP	144	96	C
	LC4256V-5T144C	256	3.3	5	TQFP	144	96	C
	LC4256V-75T144C	256	3.3	7.5	TQFP	144	96	C
	LC4256V-3T100C	256	3.3	3	TQFP	100	64	C
	LC4256V-5T100C	256	3.3	5	TQFP	100	64	C
	LC4256V-75T100C	256	3.3	7.5	TQFP	100	64	C
LC4384V	LC4384V-35FT256C	384	3.3	3.5	ftBGA	256	192	C
	LC4384V-5FT256C	384	3.3	5	ftBGA	256	192	C
	LC4384V-75FT256C	384	3.3	7.5	ftBGA	256	192	C
	LC4384V-35F256C ¹	384	3.3	3.5	fpBGA	256	192	C
	LC4384V-5F256C ¹	384	3.3	5	fpBGA	256	192	C
	LC4384V-75F256C ¹	384	3.3	7.5	fpBGA	256	192	C
	LC4384V-35T176C	384	3.3	3.5	TQFP	176	128	C
	LC4384V-5T176C	384	3.3	5	TQFP	176	128	C
	LC4384V-75T176C	384	3.3	7.5	TQFP	176	128	C

ispMACH 4000C (1.8V) Lead-Free Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4512C	LC4512C-35FTN256C	512	1.8	3.5	Lead-free ftBGA	256	208	C
	LC4512C-5FTN256C	512	1.8	5	Lead-free ftBGA	256	208	C
	LC4512C-75FTN256C	512	1.8	7.5	Lead-free ftBGA	256	208	C
	LC4512C-35FN256C ¹	512	1.8	3.5	Lead-free fpBGA	256	208	C
	LC4512C-5FN256C ¹	512	1.8	5	Lead-free fpBGA	256	208	C
	LC4512C-75FN256C ¹	512	1.8	7.5	Lead-free fpBGA	256	208	C
	LC4512C-35TN176C	512	1.8	3.5	Lead-free TQFP	176	128	C
	LC4512C-5TN176C	512	1.8	5	Lead-free TQFP	176	128	C
	LC4512C-75TN176C	512	1.8	7.5	Lead-free TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

ispMACH 4000C (1.8V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t _{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-5TN48I	32	1.8	5	Lead-free TQFP	48	32	I
	LC4032C-75TN48I	32	1.8	7.5	Lead-free TQFP	48	32	I
	LC4032C-10TN48I	32	1.8	10	Lead-free TQFP	48	32	I
	LC4032C-5TN44I	32	1.8	5	Lead-free TQFP	44	30	I
	LC4032C-75TN44I	32	1.8	7.5	Lead-free TQFP	44	30	I
	LC4032C-10TN44I	32	1.8	10	Lead-free TQFP	44	30	I
LC4064C	LC4064C-5TN100I	64	1.8	5	Lead-free TQFP	100	64	I
	LC4064C-75TN100I	64	1.8	7.5	Lead-free TQFP	100	64	I
	LC4064C-10TN100I	64	1.8	10	Lead-free TQFP	100	64	I
	LC4064C-5TN48I	64	1.8	5	Lead-free TQFP	48	32	I
	LC4064C-75TN48I	64	1.8	7.5	Lead-free TQFP	48	32	I
	LC4064C-10TN48I	64	1.8	10	Lead-free TQFP	48	32	I
	LC4064C-5TN44I	64	1.8	5	Lead-free TQFP	44	30	I
	LC4064C-75TN44I	64	1.8	5	Lead-free TQFP	44	30	I
LC4128C	LC4128C-10TN128I	128	1.8	5	Lead-free TQFP	128	92	I
	LC4128C-75TN128I	128	1.8	7.5	Lead-free TQFP	128	92	I
	LC4128C-10TN128I	128	1.8	10	Lead-free TQFP	128	92	I
	LC4128C-5TN100I	128	1.8	5	Lead-free TQFP	100	64	I
	LC4128C-75TN100I	128	1.8	7.5	Lead-free TQFP	100	64	I
	LC4128C-10TN100I	128	1.8	10	Lead-free TQFP	100	64	I

ispMACH 4000V (3.3V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t_{PD}	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-75TN48E	32	3.3	7.5	Lead-free TQFP	48	32	E
	LC4032V-75TN44E	32	3.3	7.5	Lead-free TQFP	44	30	E
LC4064V	LC4064V-75TN100E	64	3.3	7.5	Lead-free TQFP	100	64	E
	LC4064V-75TN48E	64	3.3	7.5	Lead-free TQFP	48	32	E
	LC4064V-75TN44E	64	3.3	7.5	Lead-free TQFP	44	30	E
LC4128V	LC4128V-75TN144E	128	3.3	7.5	Lead-free TQFP	144	96	E
	LC4128V-75TN128E	128	3.3	7.5	Lead-free TQFP	128	92	E
	LC4128V-75TN100E	128	3.3	7.5	Lead-free TQFP	100	64	E
LC4256V	LC4256V-75TN176E	256	3.3	7.5	Lead-free TQFP	176	128	E
	LC4256V-75TN144E	256	3.3	7.5	Lead-free TQFP	144	96	E
	LC4256V-75TN100E	256	3.3	7.5	Lead-free TQFP	100	64	E

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 4000V/B/C/Z family:

- TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#)
- TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#)

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
July 2003	17z	Changed device status for LC4064ZC and LC4128ZC to production release and updated/added AC and DC parameters as well as ordering part numbers for LC4064ZC and LC4128ZC devices.
		Improved leakage current specifications for ispMACH 4000Z. For ispMACH 4000V/B/C IIL, IIH condition now includes 0V and 3.6V end points ($0 \leq V_{IN} \leq 3.6V$).
		Added 132-ball chip scale BGA power supply and NC connections.
		Added 132-ball chip scale BGA logic signal connections for LC4064ZC, LC4128ZC and LC4256ZC devices.
		Added lead-free package designators.
October 2003	18z	Hot socketing characteristics footnote 1. has been enhanced; Insensitive to sequence of VCC or VCCO. However, assumes monotonic rise/fall rates for Vcc and Vcco, provided $(V_{IN} - VCCO) \leq 3.6V$.
		Improved LC4064ZC t_S to 2.5ns, t_{ST} to 2.7ns and f_{MAX} (Ext.) to 175MHz, LC4128ZC t_{CO} to 3.5ns and f_{MAX} (Ext.) to 161MHz (version v.2.1).
		Improved associated internal timing numbers and timing adders (version v.2.1).
		Added ispMACH 4000V/B/C/Z ORP Reference Tables.
		Enhanced ORP information in device pinout tables consistent with the ORP Combinations for I/O Blocks tables (table 6, 7, 8 and 9 in page 9-11).
		Corrected GLB/MC/Pad information in the 256-fpBGA pinouts for the LC4256V/B/C 160-I/O version.
		Added the ispMACH 4000 Family Speed Grade Offering table.
		Added the ispMACH 4128ZC Industrial and Automotive Device OPNs
December 2003	19z	Added the ispMACH 4032ZC and 4064ZC Industrial and Automotive Device OPNs